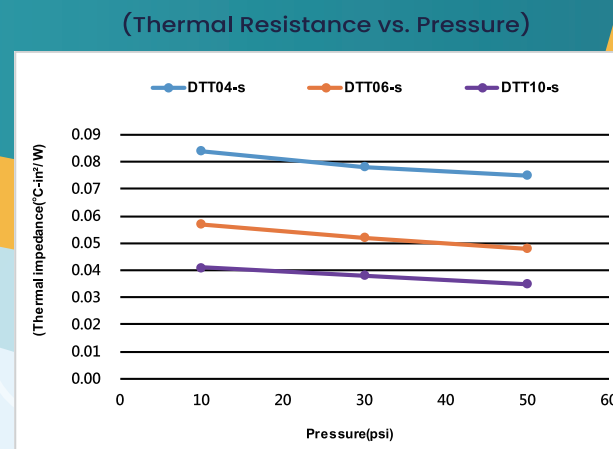


Lightweight Thermal Conductive Putty DTT

4.0~10.0 W/m*K

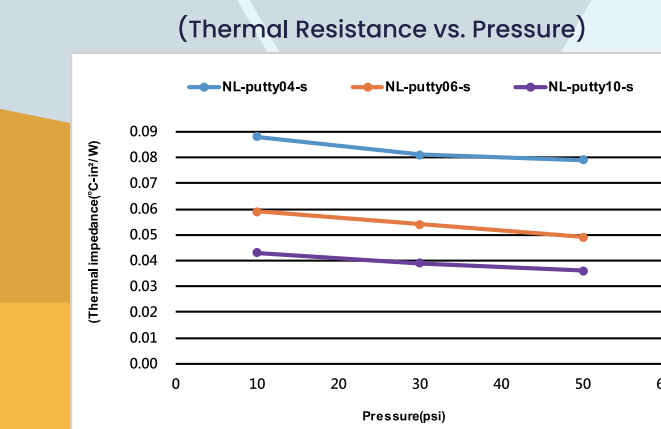


LiPOLY's DTT04-s/DTT06-s/DTT10-s series is a low-density gel gap filler with a thermal conductivity range of 4.0~10.0 W/m*K. Its low-density and lightweight characteristics enhance product performance, reduce production costs, and minimize material usage and energy consumption. It is commonly used in electronic products and automotive electronic devices.



Non-Silicone Lightweight Thermal Conductive Putty NL-putty

4.0~10.0 W/m*K



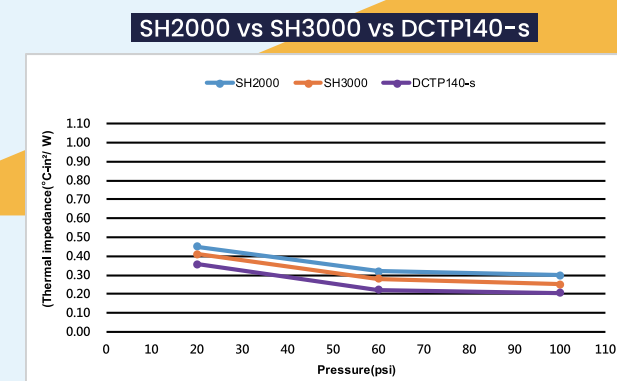
LiPOLY's NL-putty series is a non-silicone, low-density gel gap filler. Its lightweight and low-density properties enhance product performance, reduce production costs, and minimize material usage and energy consumption. It is commonly used in electronic products and automotive electronic devices. With a thermal conductivity range of 4.0~10.0 W/m*K, its non-silicone nature eliminates low-molecular siloxane emissions, preventing electrical contact failures. It features high deformability, allowing flexible gap adaptation and tolerance compensation. The material overcomes issues like overflow and drying, improves thermal conductivity, and is suitable for automated dispensing production.

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SHIU LI TECHNOLOGY CO.,LTD

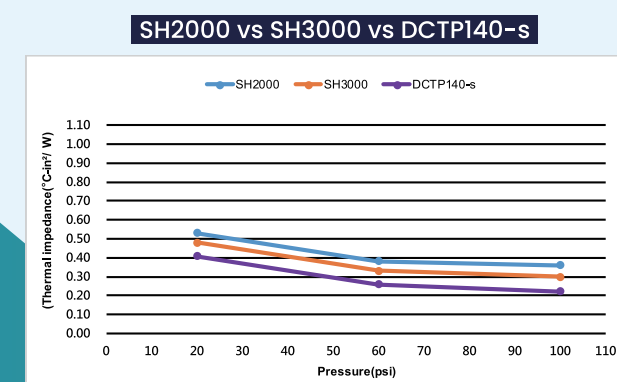
Insulated Thermal Conductive PR/ SH/ DCTP/ SP/ TP/ HC

0.8~4.5 W/m*K

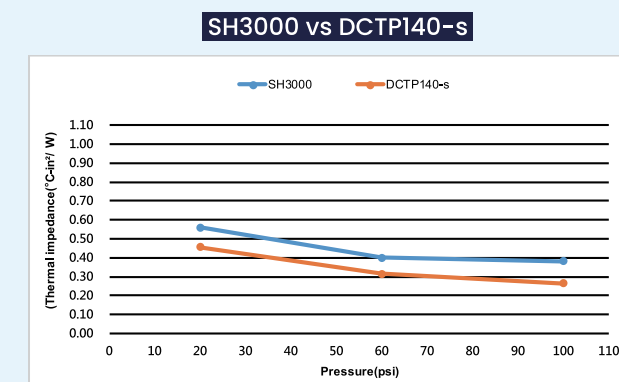
LiPOLY's PR, SH, and DCTP series are high-insulation materials with thickness ranging from 0.10 to 0.45 mm and breakdown voltages of 4~12 KV. These materials offer excellent tensile strength and resistance to high-torque screw fastening, making them ideal for high-power transistors and electrical equipment. Made from polyimide and fiberglass, they are suitable for applications requiring high heat resistance, thermal conductivity, and insulation, such as high-temperature equipment insulation, power supplies, and electric vehicle battery modules. They provide reliable insulation and prevent electrical failures. LiPOLY's SP, TP, and HC series are three-dimensional thermally conductive insulating silicone rubber caps and tubes produced through a specialized manufacturing process. Since excellent thermal conductivity, insulation, shock resistance, and easy assembly, they are widely used for heat transistors, such as TO220 and TO3P.



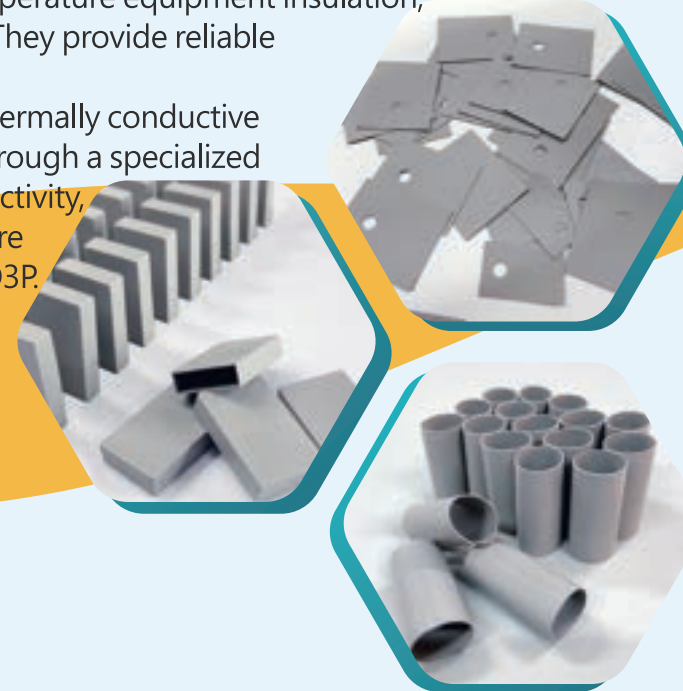
(0.25mm Thermal Resistance vs. Pressure)



(0.30mm Thermal Resistance vs. Pressure)



(0.45mm Thermal Resistance vs. Pressure)

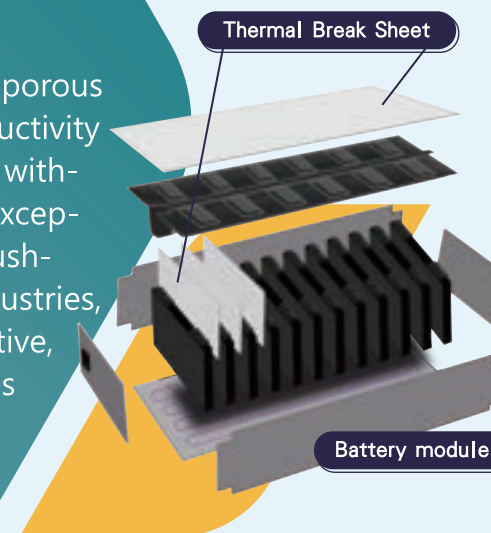


Thermal Break Sheet -Industrial industry AS17-s

0.028 W/m*K

AS17-s thermal insulation material is a composite fiber made from porous silica, alumina, and other materials, with an ultra-low thermal conductivity of 0.028 W/m*K. AS17-s is a high-performance material capable of withstanding high temperatures up to 1300°C and is renowned for its exceptional thermal insulation, outstanding noise blocking, cushioning, and fireproof properties. It is widely used across various industries, including aerospace, energy storage, military, new energy, automotive, firefighting, and rail transportation. The application range of AS17-s continues to expand, and as technology advances further, we can expect to see its use in more emerging fields, further highlighting its significance in modern industry and daily life.

- / Excellent thermal insulation performance with a thermal conductivity of 0.028 W/m*K
- / Superior thermal stability, suitable for long-term use at 1300°C
- / Outstanding aging resistance
- / High friction coefficient and strong stability, providing long-term physical support for various carriers
- / Compliant with RoHS and REACH standards
- / Available in both roll and sheet formats
- / Surface has a felt-like texture



Thermal Break Sheet -Electronics industry AS27-s

0.009 W/m*K

AS27-s insulation material is composed of nanoscale porous silica, carbon, and other materials, featuring an extremely low thermal conductivity of 0.009 W/m*K, making it one of the lowest known solid thermal conductors. AS27-s is a high-performance material with ultra-low density and exceptional properties, including superior thermal insulation, excellent noise blocking, cushioning, and fireproof capabilities. It is widely used across various fields such as aerospace, electronics, energy, transportation, consumer electronics, and home appliances. The application range of AS27-s continues to expand, and with further technological advancements, it is expected to see use in more emerging fields, driving its significance in modern industry and daily life.

- / Thermal conductivity: 0.009 W/m*K
- / Excellent thermal insulation
- / Customizable die-cutting
- / Flexible and conforms to surfaces
- / Lightweight, density: 0.09 g/cm³
- / Available in both roll and sheet formats
- / Compliant with RoHS and REACH standards



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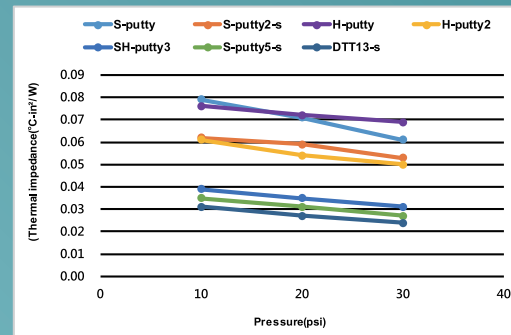
Thermal Conductive Putty

S-putty / H-putty / SH-putty / DTT

3.5~13.0 W/m*K

LiPOLY's putty series is a thermally conductive gel gap filler with a thermal conductivity range of 3.5~13.0 W/m*K. It features high deformability, extremely low thermal resistance, and low stress, allowing it to flexibly adapt to gaps and compensate for tolerances. Unlike thermal pastes, it avoids issues such as overflow and drying. It is an ideal choice for automated dispensing production when used with LiPOLY's dedicated putty dispensing equipment.

(Thermal Resistance vs. Pressure)



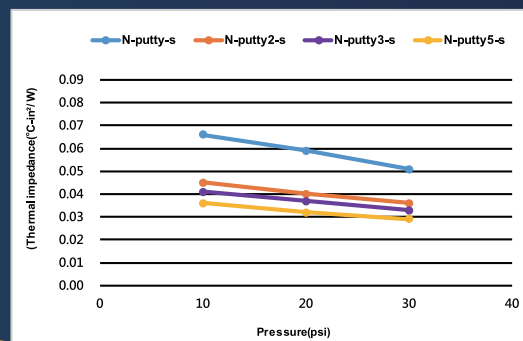
Non-Silicon Thermal Conductive Putty

N-putty

3.5~9.0 W/m*K

LiPOLY's N-putty is a non-silicone thermally conductive gel with a thermal conductivity range of 3.5~9.0 W/m*K. It is free of low-molecular siloxane emissions, preventing electrical contact failures, making it suitable for optical products and sensitive electronic components. With extremely low thermal resistance and low stress, it flexibly adapts to gaps and compensates for tolerances, overcoming issues like overflow and drying seen with thermal pastes. It is an ideal choice for automated dispensing production when paired with LiPOLY's dedicated putty dispensing equipment.

(Thermal Resistance vs. Pressure)



LiPOLY[®]
SHIU LI TECHNOLOGY CO.,LTD

High Thermal Conductive Gap Filler

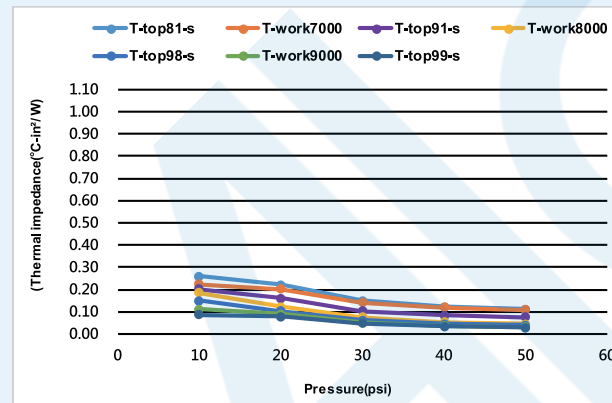
T-top / T-work

8.0~24.0 W/m*K

LiPOLY's T series is a high-performance thermal pad featuring excellent insulation, compressibility, and softness, allowing it to fill gaps effectively. It delivers extremely low thermal resistance and can be customized for die-cutting.

- / Gap between CPU and heatsink
- / Gap between PC components and heatsink
- / High-performance chips
- / Communication devices
- / High-speed storage
- / Flat panel displays
- / Power supplies

(Thermal Resistance vs. Pressure)



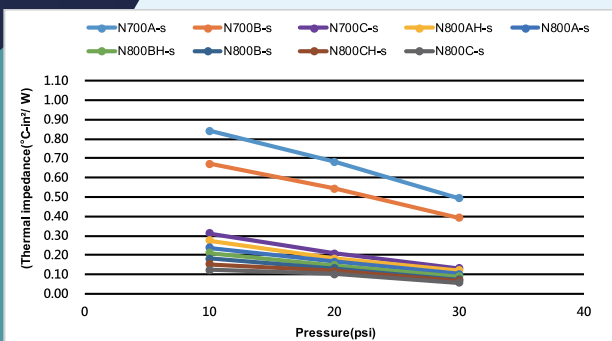
Non-Silicone Thermal Conductive Pad

N700 / N800

2.5~17.0 W/m*K

LiPOLY's N series uses non-silicone resin materials, free of low-molecular siloxane emissions, preventing electrical contact failures. It is suitable for optical products and sensitive electronic components. With a thermal conductivity range of 2.5~17.0 W/m*K, this gap filler offers excellent thermal performance. Featuring a Shore OO hardness of 50~60, it provides low thermal resistance, with N800C-s achieving a remarkable thermal conductivity of up to 17.0 W/m*K.

(Thermal Resistance vs. Pressure)



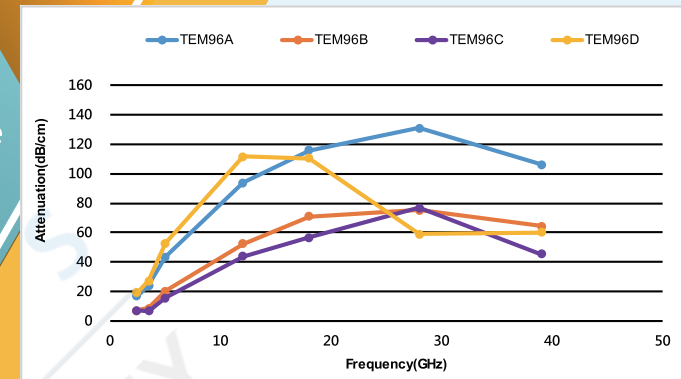
Thermal Conductive RF Absorber Pad

TEM

2.0~5.0 W/m*K

LiPOLY's TEM series is a composite pad combining thermal conductivity and electromagnetic wave absorption functions. With a thermal conductivity range of 2.0~5.0 W/m*K, it serves as a gap filler material suitable for frequencies from 10MHz to 77GHz. The product features flexibility, compressibility, and can be customized through die-cutting. Leveraging its advanced R&D capabilities, LiPOLY provides cutting-edge thermal management solutions to meet the unique demands of today's advanced products.

(Frequency vs. Attenuation)



5G mmWave Thermal Conductive Gel Pad

DTT

3.0~5.0 W/m*K

LiPOLY DTT is a soft thermally conductive gel pad designed specifically for network communication applications. It can focus on Dk and Df to reduce interference in RF modules. With a thermal conductivity of 3.0~5.0 W/m*K, the DTT pad can also be customized through cutting and die-cutting, enabling a wider range of applications.

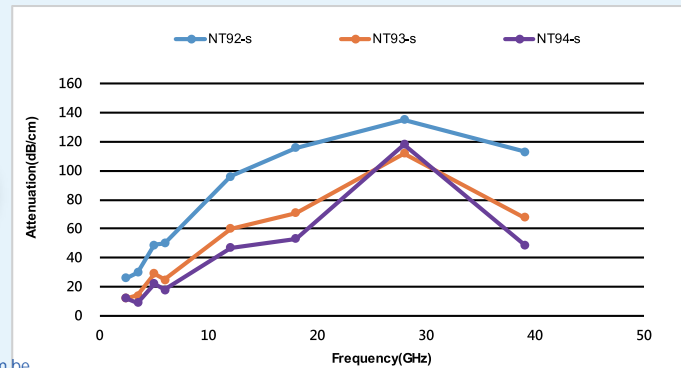
Non-Silicone Thermal Conductive RF Absorber Pad

NT

2.0~4.0 W/m*K

The NT series is made from non-silicone resin materials, free of low-molecular siloxane emissions. It is a composite pad with both thermal conductivity and electromagnetic wave absorption capabilities. With a thermal conductivity range of 2.0~4.0 W/m*K, it serves as a gap filler material suitable for frequencies from 10MHz to 77GHz. The pad features flexibility, compressibility, and can be customized for die-cutting.

(Frequency vs. Attenuation)



Thermal Conductive Tape

ST6000-S

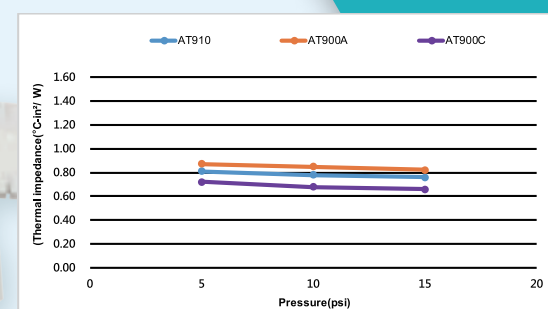
1.8 W/m*K

AT Series

0.9~3.5 W/m*K

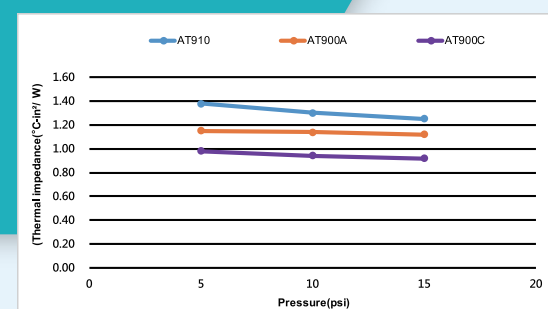
Silicone-based thermal adhesive tape ST6000-S offers strong adhesion and excellent thermal conductivity. It is suitable for bonding heatsinks, solar photovoltaic modules, and LED modules, making it ideal for applications requiring secure adhesion with thermal performance. LiPOLY's ST series is a heat-resistant, insulating thermal adhesive tape with a temperature range of -60°C to 180°C, capable of withstanding up to 288°C for short periods. Its adhesive strength and durability increase with temperature and pressure.

AT910 vs AT900A vs AT900C



(0.15mm Thermal Resistance vs. Pressure)

AT910 vs AT900A vs AT900C



(0.25mm Thermal Resistance vs. Pressure)

Two-Part Thermal Conductive Sealing Glue

TPS

0.8~3.0 W/m*K

LiPOLY's TPS series is a two-component thermally conductive potting adhesive that cures at room or high temperatures. This liquid-flowing thermal adhesive fills air gaps around electronic components, creating a close bond with heat-generating components and heatsinks after curing. It enables efficient heat transfer, allowing electronic products to operate at high power. With a thermal conductivity range of 0.8~3.0 W/m*K, it serves as a reliable gap filler material.